General Description

The WSD3039DN56 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

The WSD3039DN56 meet the RoHS and Green Product requirement, 100% E_{AS} guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- 100% E_{AS} Guaranteed
- Green Device Available

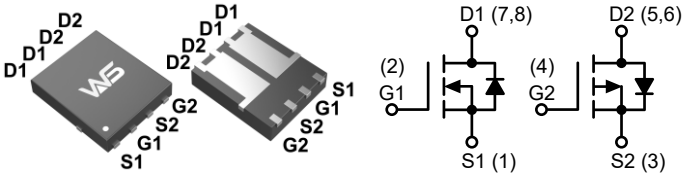
Product Summery

BV_{DSS}	$R_{DS(ON)}$	I_D
30V	14mΩ	20A
-30V	24mΩ	-16A

Applications

- Wireless charging
- Boost driver.
- Brushless motor

DFN5X6-8L Pin Configuration



Absolute Maximum Ratings (T_C=25°C, Unless Otherwise Noted)

Symbol	Parameter	Rating		Units
		N-Channel	P-Channel	
V_{DS}	Drain-Source Voltage	30	-30	V
V_{GS}	Gate-Source Voltage	±20	±20	
I_D@T_C=25°C	Continuous Drain Current, V_{GS} @ 10V [1]	20	-16	A
I_D@T_A=100°C	Continuous Drain Current, V_{GS} @ 10V [1]	10	-8	
I_{DM}	Pulsed Drain Current [2]	52	-45	
E_{AS}	Single Pulse Avalanche Energy [3]	22	45	mJ
I_{AS}	Avalanche Current	21	-30	A
P_D@T_A=25°C	Power Dissipation [4]	18	18	W
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	-55 to 150	

Thermal Data

Symbol	Parameter	Rating	Units
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient [1]	55	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case [1],(t<=10sec)	5.0	

N-Channel Electrical Characteristics (T_J=25°C, Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250μA	30	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance [2]	V_{GS}=10V , I_D=10A	---	14	23	mΩ
		V_{GS}=4.5V , I_D=5A	---	19	28	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D=250μA	1.0	1.6	2.5	V
I_{DSS}	Drain-Source Leakage Current	V_{DS}=24V , V_{GS}=0V , T_J=25°C	---	---	1.0	μA
		V_{DS}=24V , V_{GS}=0V , T_J=55°C	---	---	5.0	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
g_{fs}	Forward Transconductance	V_{DS}=5V , I_D=10A	---	16	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1.0MHz	---	2.5	5	Ω
Q_g	Total Gate Charge (4.5V)	V_{DS}=20V , V_{GS}=4.5V , I_D=10A	---	7.2	---	nC
Q_{gs}	Gate-Source Charge		---	1.4	---	
Q_{gd}	Gate-Drain Charge		---	2.2	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=15V , V_{GS}=10V , R_G=3.3Ω , I_D=5A	---	4.1	---	ns
T_r	Rise Time		---	9.8	---	
$T_{d(off)}$	Turn-Off Delay Time		---	15.5	---	
T_f	Fall Time		---	6.0	---	
C_{iss}	Input Capacitance	V_{DS}=15V , V_{GS}=0V , f=1.0MHz	---	572	---	pF
C_{oss}	Output Capacitance		---	81	---	
C_{rss}	Reverse Transfer Capacitance		---	65	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
I_S	Continuous Source Current [1,5]	V_G=V_D=0V , Force Current	---	---	10	A
V_{SD}	Diode Forward Voltage [2]	V_{GS}=0V , I_S=1A , T_J=25°C	---	---	1.2	V

Note:

1. The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. The E_{AS} data shows Max. rating . The test condition is V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=10A
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

P-Channel Electrical Characteristics (T_J=25°C, Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=-250μA	-30	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance [2]	V_{GS}=-10V , I_D=-7A	---	24	31	mΩ
		V_{GS}=-4.5V , I_D=-5A	---	36	52	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D=-250μA	-1.0	---	-2.5	V
I_{DSS}	Drain-Source Leakage Current	V_{DS}=-24V , V_{GS}=0V , T_J=25°C	---	---	1.0	μA
		V_{DS}=-24V , V_{GS}=0V , T_J=55°C	---	---	5.0	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
g_{fs}	Forward Transconductance	V_{DS}=-5V , I_D=-7A	---	15	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1.0MHz	---	15	30	Ω
Q_g	Total Gate Charge (-4.5V)	V_{DS}=-20V , V_{GS}=-4.5V , I_D=-7A	---	9.8	---	nC
Q_{gs}	Gate-Source Charge		---	2.2	---	
Q_{gd}	Gate-Drain Charge		---	3.4	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=-15V , V_{GS}=-10V , R_G=3.3Ω , I_D=-5A	---	16.4	---	ns
T_r	Rise Time		---	20.2	---	
$T_{d(off)}$	Turn-Off Delay Time		---	55	---	
T_f	Fall Time		---	10	---	
C_{iss}	Input Capacitance	V_{DS}=-15V , V_{GS}=0V , f=1.0MHz	---	930	---	pF
C_{oss}	Output Capacitance		---	148	---	
C_{rss}	Reverse Transfer Capacitance		---	115	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
I_S	Continuous Source Current [1,5]	V_G=V_D=0V , Force Current	---	---	-8	A
V_{SD}	Diode Forward Voltage [2]	V_{GS}=0V , I_S=-1A , T_J=25°C	---	---	-1.2	V

Note:

1. The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. The E_{AS} data shows Max. rating . The test condition is V_{DD}=-25V, V_{GS}=-10V, L=0.1mH, I_{AS}=-10A
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

N-Channel Typical Characteristics

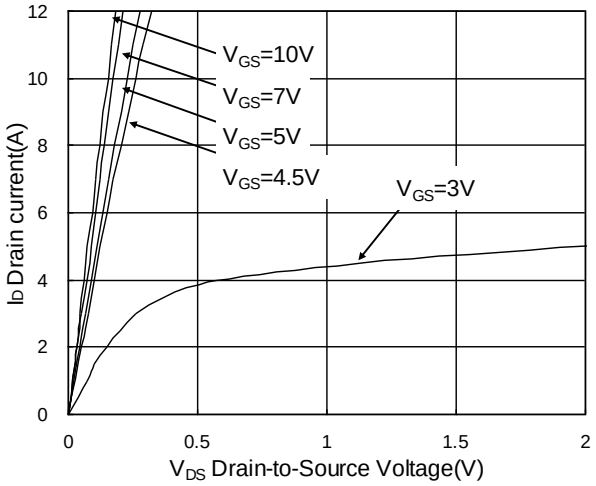


Fig.1 Typical Output Characteristics

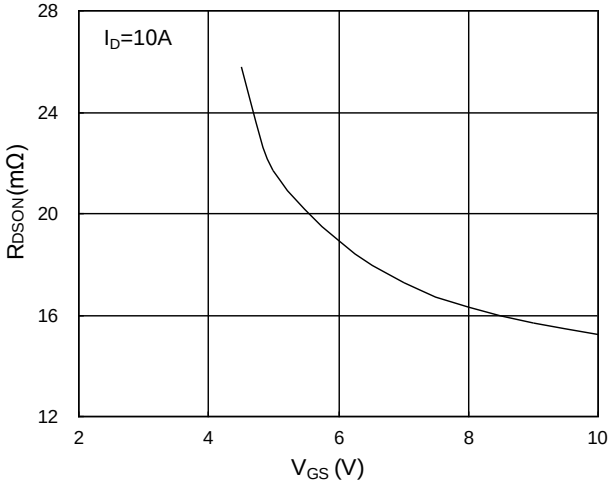


Fig.2 On-Resistance v.s Gate-Source

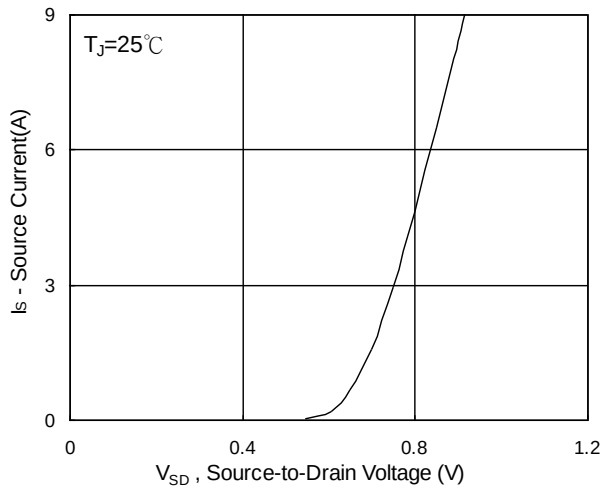


Fig.3 Forward Characteristics Of Reverse

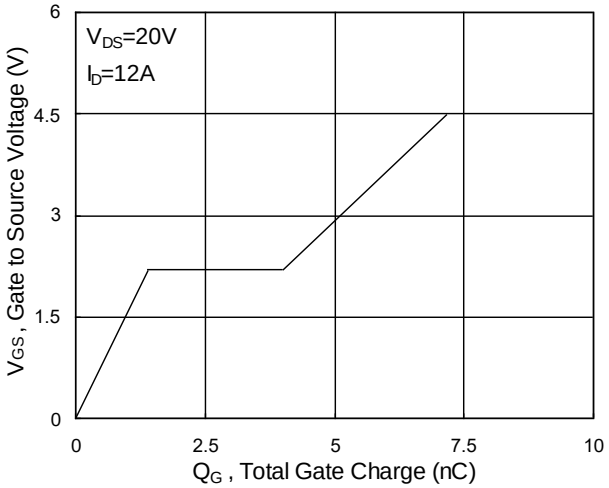


Fig.4 Gate-Charge characteristics

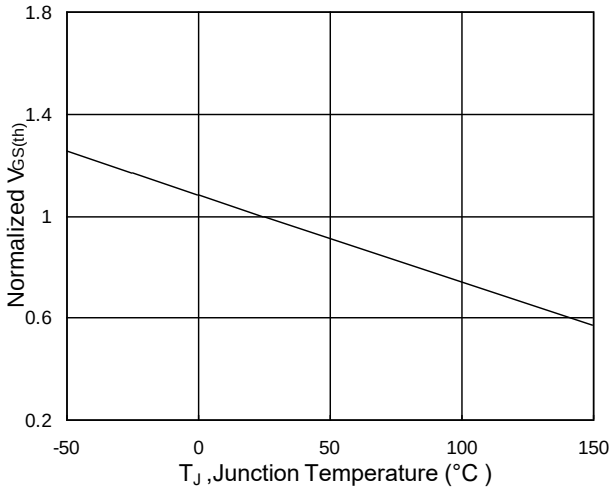


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

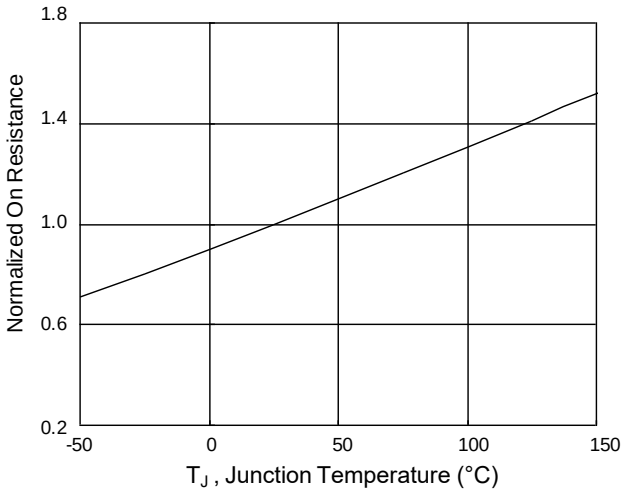


Fig.6 Normalized R_{DSON} v.s T_J

N-Channel Typical Characteristics (Cont.)

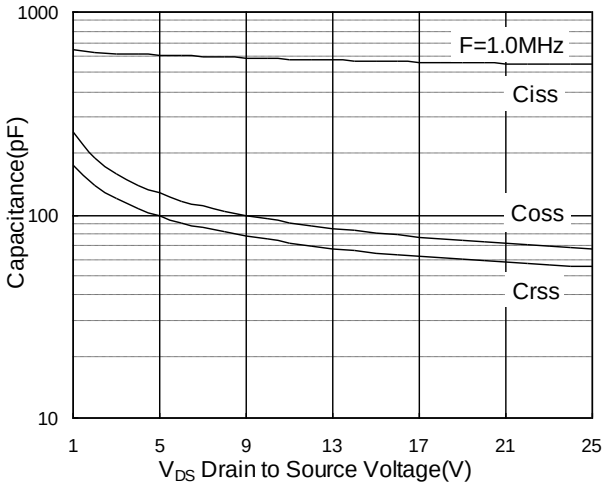


Fig.7 Capacitance

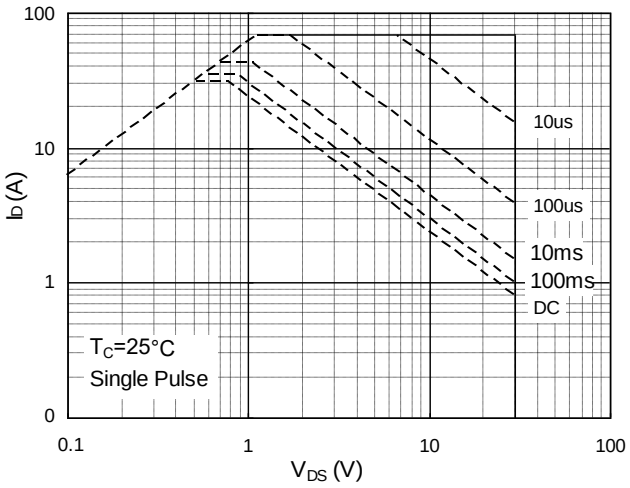


Fig.8 Safe Operating Area

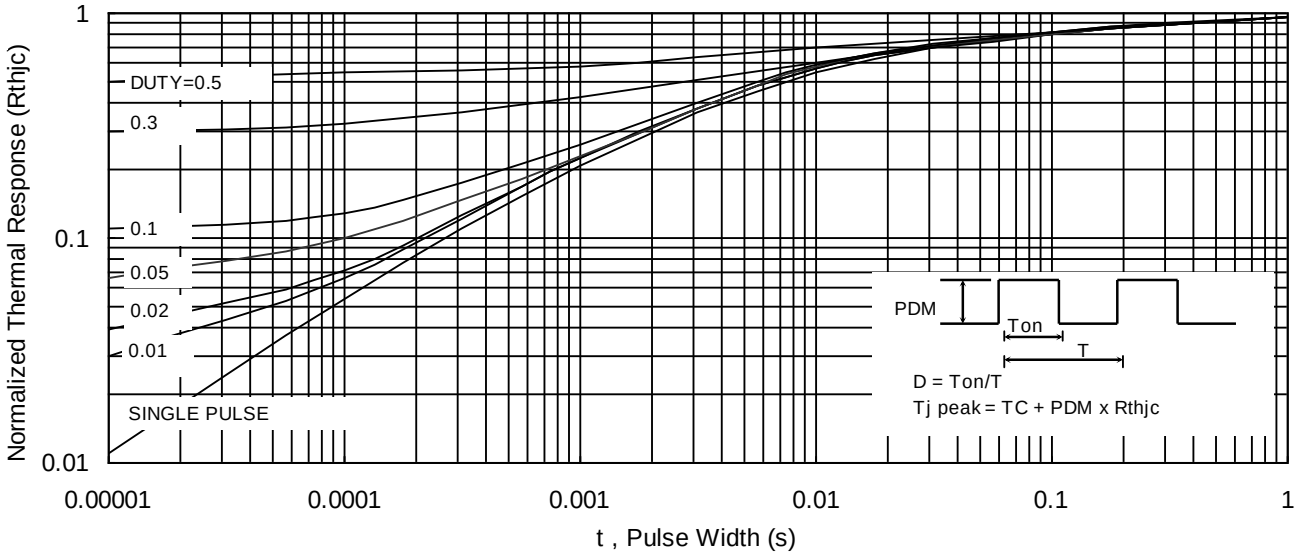


Fig.9 Normalized Maximum Transient Thermal Impedance

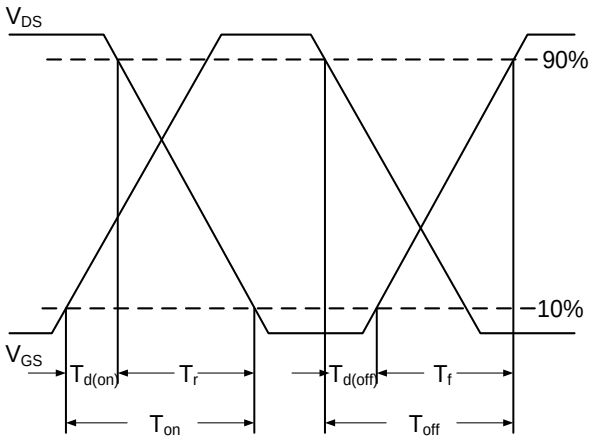


Fig.10 Switching Time Waveform

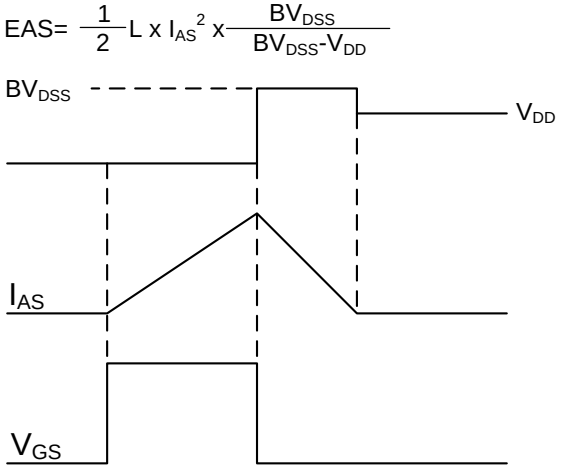


Fig.11 Unclamped Inductive Waveform

P-Channel Typical Characteristics

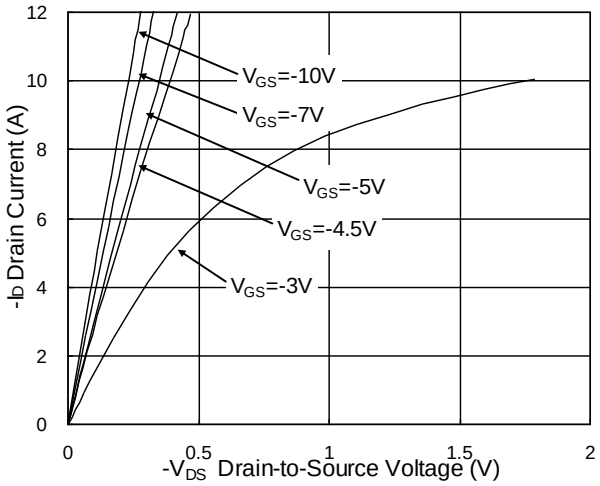


Fig.1 Typical Output Characteristics

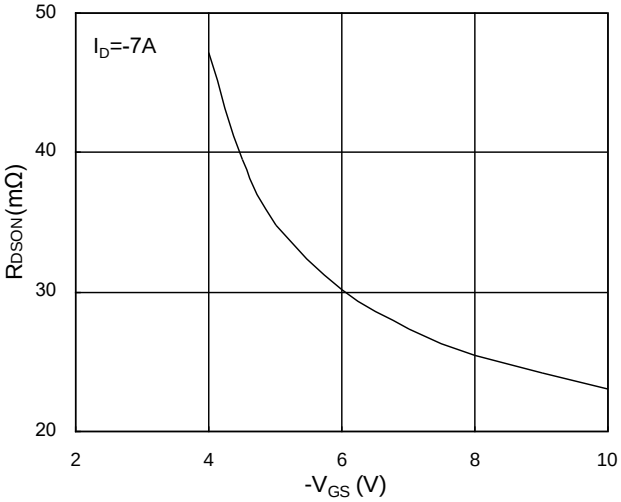


Fig.2 On-Resistance v.s Gate-Source

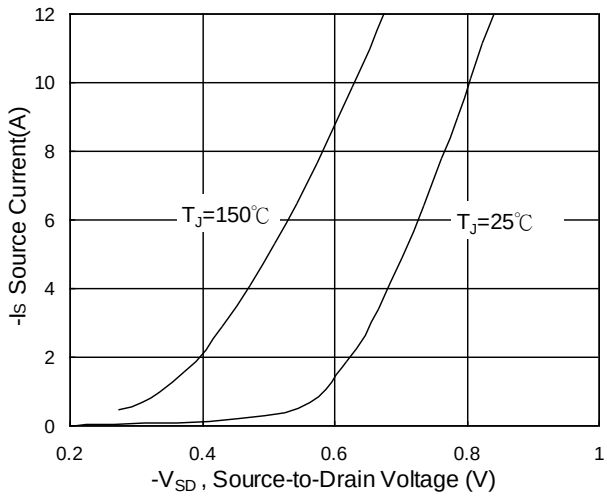


Fig.3 Forward Characteristics Of Reverse

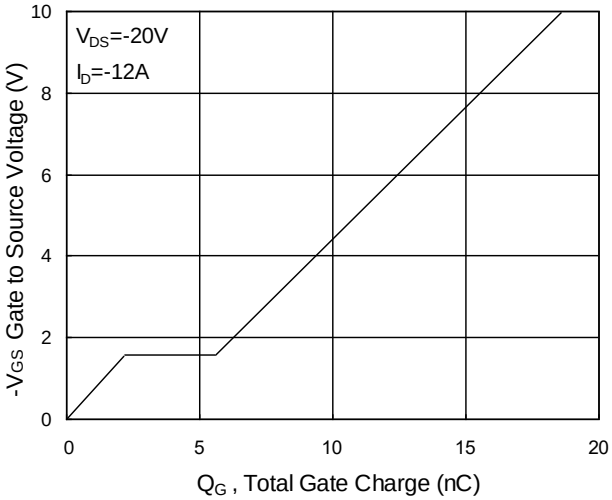


Fig.4 Gate-Charge Characteristics

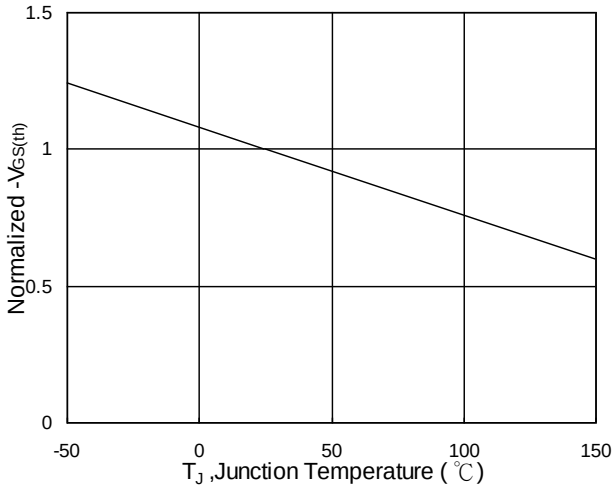


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

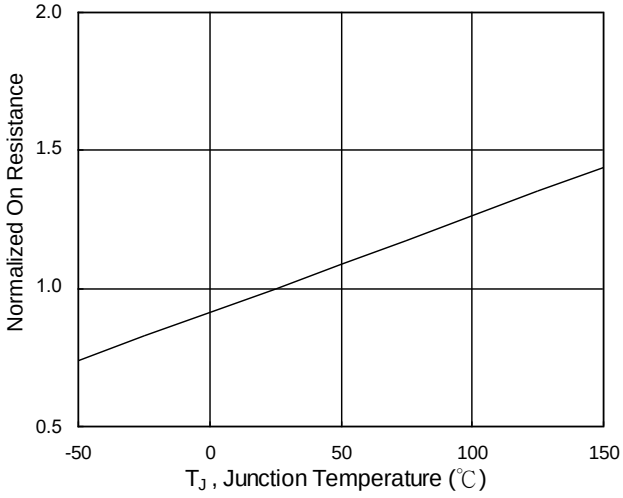


Fig.6 Normalized R_{DSON} v.s T_J

P-Channel Typical Characteristics (Cont.)

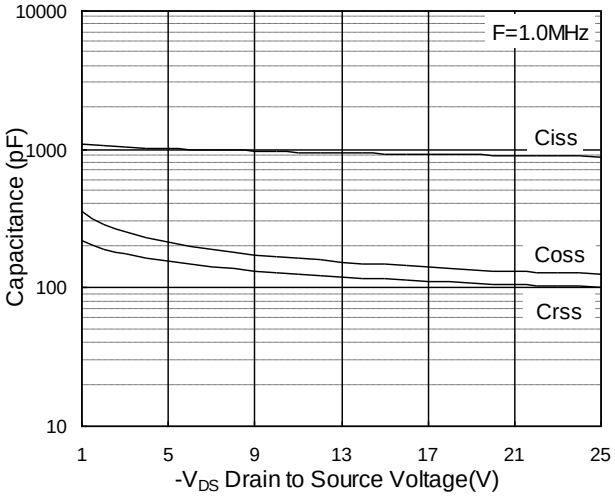


Fig.7 Capacitance

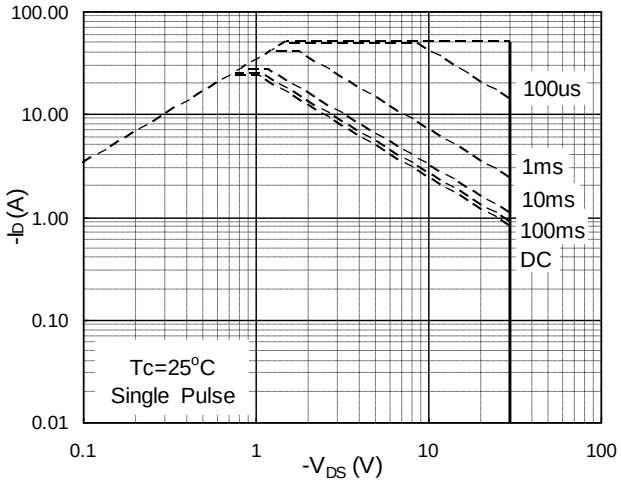


Fig.8 Safe Operating Area

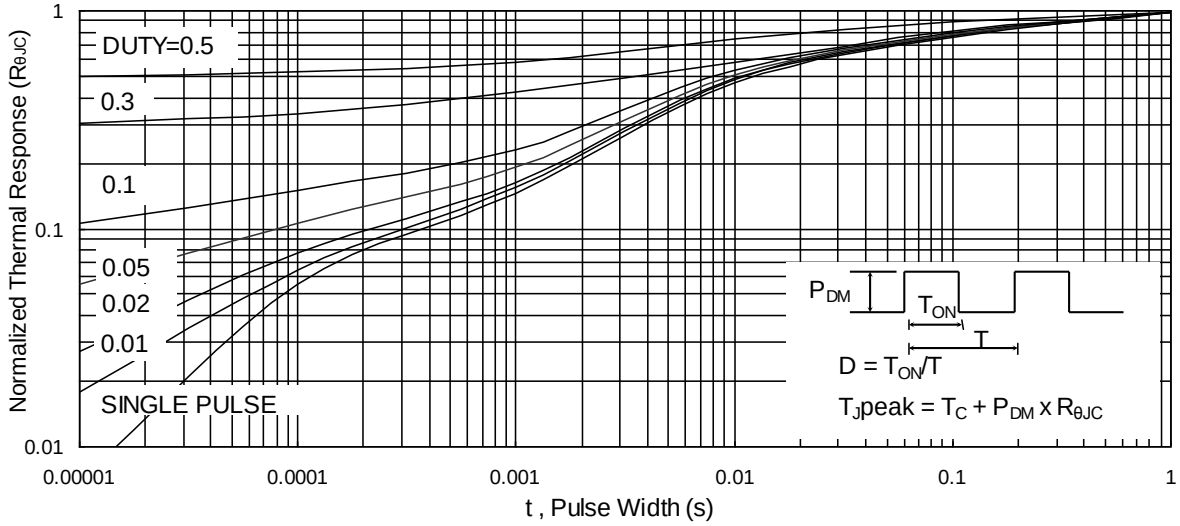


Fig.9 Normalized Maximum Transient Thermal Impedance

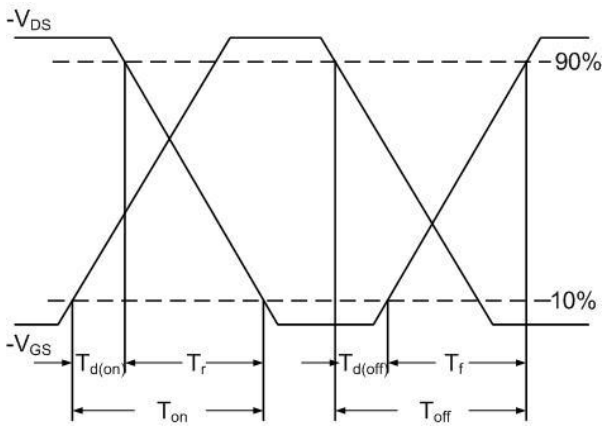


Fig.10 Switching Time Waveform

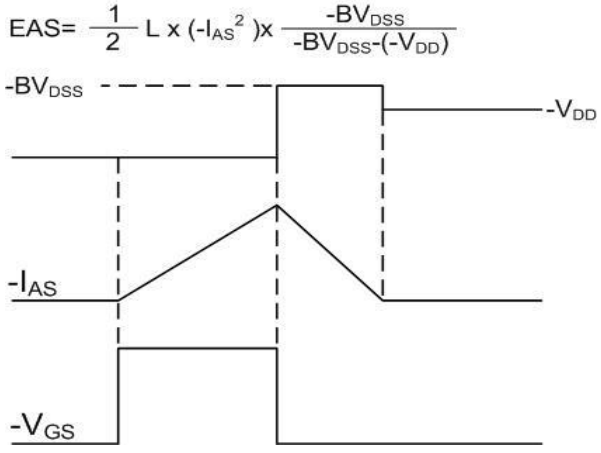
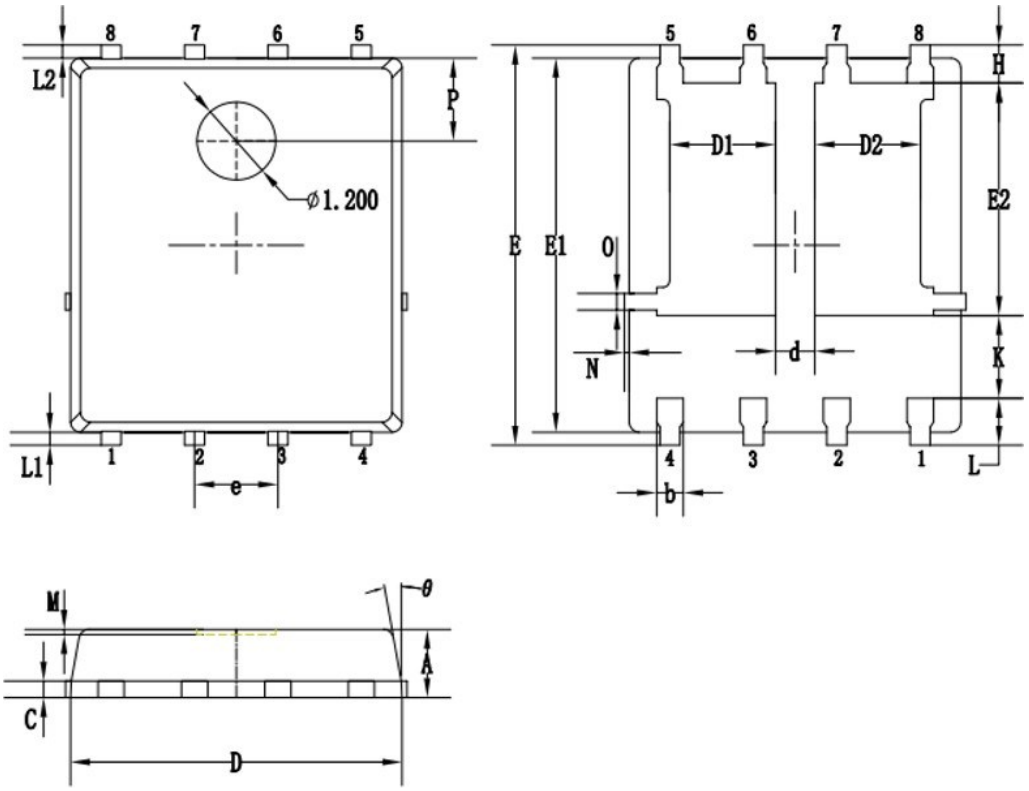


Fig.11 Unclamped Inductive Waveform

Packaging information



SYMBOLS	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.05	1.20
b	0.35	0.40	0.50
C	0.20	0.25	0.35
D	4.90	5.05	5.20
D1/D2	1.51	1.61	1.71
d	0.50	0.60	0.70
E	6.00	6.15	6.30
E1	5.60	5.75	5.90
E2	3.47	3.57	3.67
e	1.27 BSC.		
H	0.48	0.58	0.68
K	1.17	1.27	1.37
L	0.64	0.74	0.84
L1/L2	0.20 REF.		
θ	8°	10°	12°
M	0.08 REF.		
N	0	-	0.15
O	0.25 REF.		
P	1.28 REF.		

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